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Kind regards,

Team Nexperia

PDTC124X series

NPN resistor-equipped transistors; R1 = 22 kΩ, R2 = 47 kΩ

Rev. 07 — 16 November 2009

Product data sheet

1. Product profile

1.1 General description

NPN Resistor-Equipped Transistors (RET) family.

Table 1. Product overview

Type number	Package			PNP complement
	NXP	JEITA	JEDEC	
PDTC124XE	SOT416	SC-75	-	PDTA124XE
PDTC124XEF	SOT490	SC-89	-	PDTA124XEF
PDTC124XK	SOT346	SC-59A	TO-236	PDTA124XK
PDTC124XM	SOT883	SC-101	-	PDTA124XM
PDTC124XS ^[1]	SOT54	SC-43A	TO-92	PDTA124XS
PDTC124XT	SOT23	-	TO-236AB	PDTA124XT
PDTC124XU	SOT323	SC-70	-	PDTA124XU

[1] Also available in SOT54A and SOT54 variant packages (see [Section 2](#)).

1.2 Features

- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs

1.3 Applications

- General-purpose switching and amplification
- Inverter and interface circuits
- Circuit drivers

1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CEO}	collector-emitter voltage	open base	-	-	50	V
I _O	output current		-	-	100	mA
R ₁	bias resistor 1 (input)		15.4	22	28.6	kΩ
R _{2/R₁}	bias resistor ratio		1.7	2.1	2.6	



2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
SOT54			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
SOT54A			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
SOT54 variant			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
SOT23; SOT323; SOT346; SOT416; SOT490			
1	input (base)		
2	GND (emitter)		
3	output (collector)		
SOT883			
1	input (base)		
2	GND (emitter)		
3	output (collector)		 Transparent top view

3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
PDTC124XE	SC-75	plastic surface mounted package; 3 leads	SOT416
PDTC124XEF	SC-89	plastic surface mounted package; 3 leads	SOT490
PDTC124XK	SC-59A	plastic surface mounted package; 3 leads	SOT346
PDTC124XM	SC-101	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.5 mm	SOT883
PDTC124XS ^[1]	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
PDTC124XT	-	plastic surface mounted package; 3 leads	SOT23
PDTC124XU	SC-70	plastic surface mounted package; 3 leads	SOT323

[1] Also available in SOT54A and SOT54 variant packages (see [Section 2](#) and [Section 9](#)).

4. Marking

Table 5. Marking codes

Type number	Marking code ^[1]
PDTC124XE	32
PDTC124XEF	32
PDTC124XK	51
PDTC124XM	DZ
PDTC124XS	TC124X
PDTC124XT	*46
PDTC124XU	*51

[1] * = -: made in Hong Kong

* = p: made in Hong Kong

* = t: made in Malaysia

* = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CBO}	collector-base voltage	open emitter	-	50	V
V _{CEO}	collector-emitter voltage	open base	-	50	V
V _{EBO}	emitter-base voltage	open collector	-	7	V
V _I	input voltage				
	positive		-	+40	V
	negative		-	-7	V
I _O	output current		-	100	mA
I _{CM}	peak collector current	single pulse; t _p ≤ 1 ms	-	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT416	[1]	-	150	mW
	SOT490	[1][2]	-	250	mW
	SOT346	[1]	-	250	mW
	SOT883	[2][3]	-	250	mW
	SOT54	[1]	-	500	mW
	SOT23	[1]	-	250	mW
	SOT323	[1]	-	200	mW
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		-	150	°C
T _{amb}	ambient temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB with 60 µm copper strip line, standard footprint.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R _{th(j-a)}	thermal resistance from junction to ambient	in free air				
	SOT416	[1]	-	-	833	K/W
	SOT490	[1][2]	-	-	500	K/W
	SOT346	[1]	-	-	500	K/W
	SOT883	[2][3]	-	-	500	K/W
	SOT54	[1]	-	-	250	K/W
	SOT23	[1]	-	-	500	K/W
	SOT323	[1]	-	-	625	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

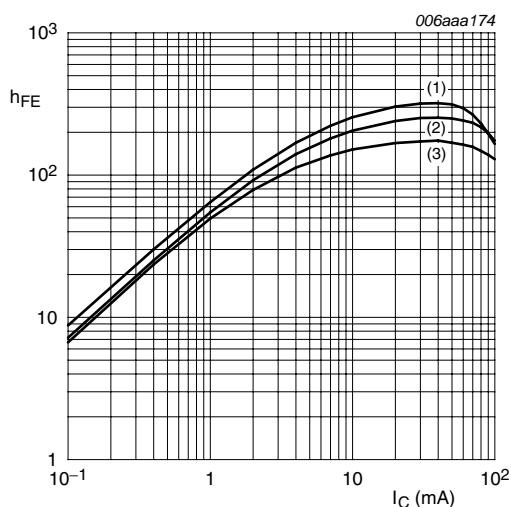
[3] Device mounted on an FR4 PCB with 60 µm copper strip line, standard footprint.

7. Characteristics

Table 8. Characteristics

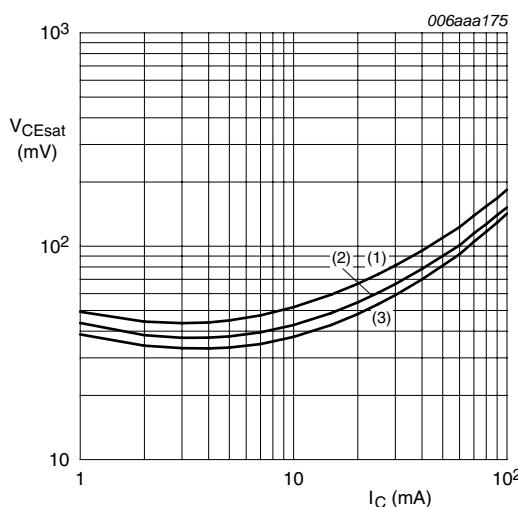
T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I _{CBO}	collector-base cut-off current	V _{CB} = 50 V; I _E = 0 A	-	-	100	nA
I _{CEO}	collector-emitter cut-off current	V _{CE} = 30 V; I _B = 0 A	-	-	1	µA
		V _{CE} = 30 V; I _B = 0 A; T _j = 150 °C	-	-	50	µA
I _{EBO}	emitter-base cut-off current	V _{EB} = 5 V; I _C = 0 A	-	-	120	µA
h _{FE}	DC current gain	V _{CE} = 5 V; I _C = 5 mA	80	-	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = 10 mA; I _B = 0.5 mA	-	-	150	mV
V _{I(off)}	off-state input voltage	V _{CE} = 5 V; I _C = 100 µA	-	0.8	0.5	V
V _{I(on)}	on-state input voltage	V _{CE} = 300 mV; I _C = 2 mA	2	1.1	-	V
R1	bias resistor 1 (input)		15.4	22	28.6	kΩ
R2/R1	bias resistor ratio		1.7	2.1	2.6	
C _c	collector capacitance	V _{CB} = 10 V; I _E = i _e = 0 A; f = 1 MHz	-	-	2.5	pF



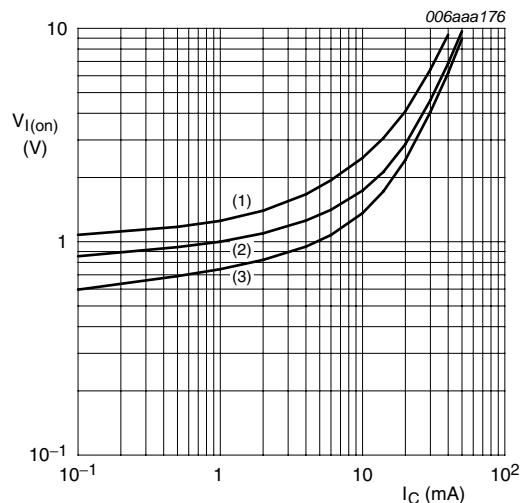
$V_{CE} = 5 \text{ V}$
(1) $T_{amb} = 100 \text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25 \text{ }^{\circ}\text{C}$
(3) $T_{amb} = -40 \text{ }^{\circ}\text{C}$

Fig 1. DC current gain as a function of collector current; typical values



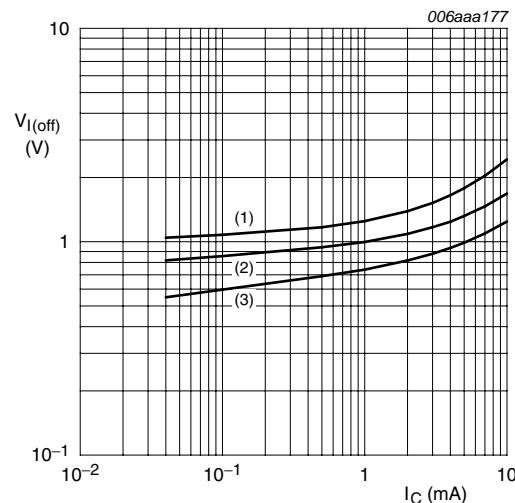
$I_C/I_B = 20$
(1) $T_{amb} = 100 \text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25 \text{ }^{\circ}\text{C}$
(3) $T_{amb} = -40 \text{ }^{\circ}\text{C}$

Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values



$V_{CE} = 0.3 \text{ V}$
(1) $T_{amb} = -40 \text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25 \text{ }^{\circ}\text{C}$
(3) $T_{amb} = 100 \text{ }^{\circ}\text{C}$

Fig 3. On-state input voltage as a function of collector current; typical values



$V_{CE} = 5 \text{ V}$
(1) $T_{amb} = -40 \text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25 \text{ }^{\circ}\text{C}$
(3) $T_{amb} = 100 \text{ }^{\circ}\text{C}$

Fig 4. Off-state input voltage as a function of collector current; typical values

8. Package outline

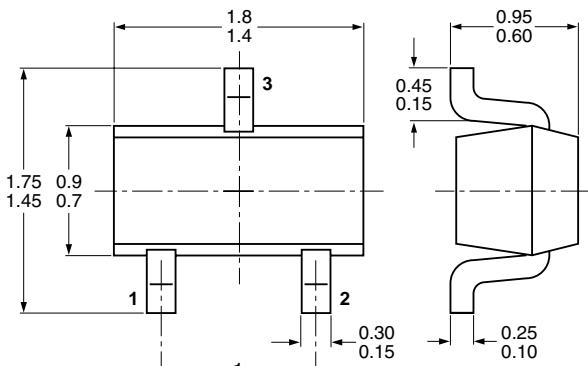


Fig 5. Package outline SOT416 (SC-75)

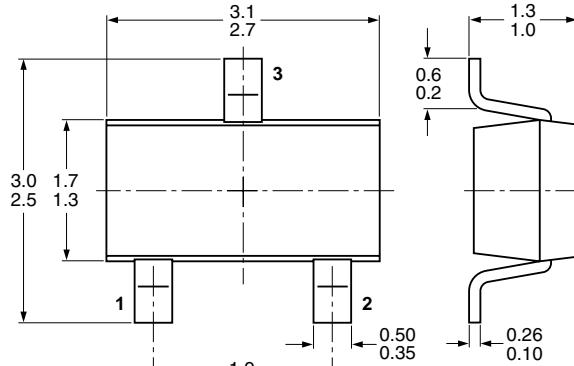


Fig 6. Package outline SOT346 (SC-59A/TO-236)

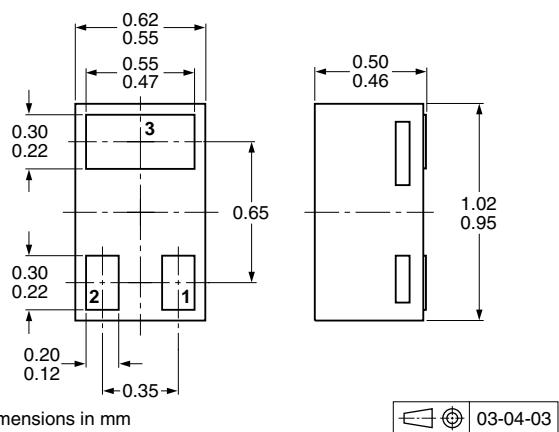


Fig 7. Package outline SOT883 (SC-101)

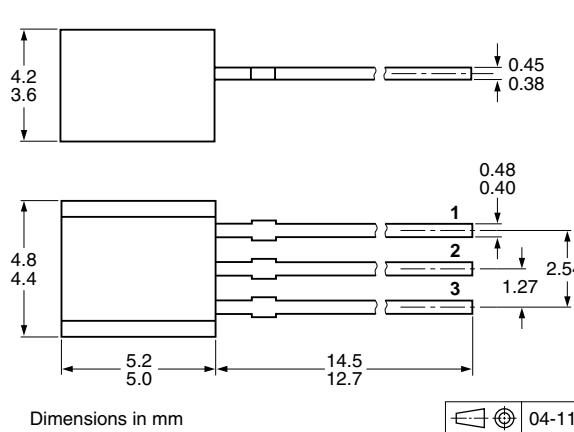


Fig 8. Package outline SOT54 (SC-43A/TO-92)

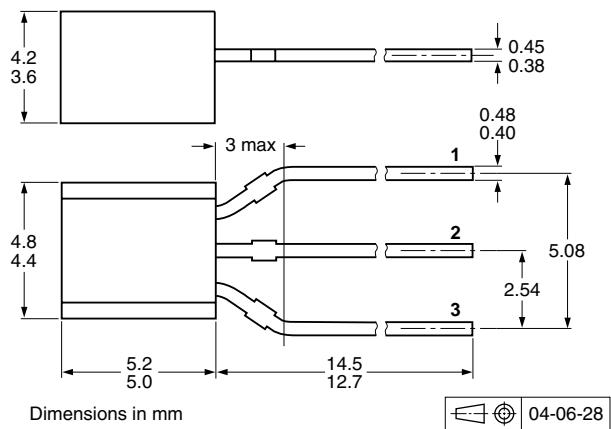


Fig 9. Package outline SOT54A

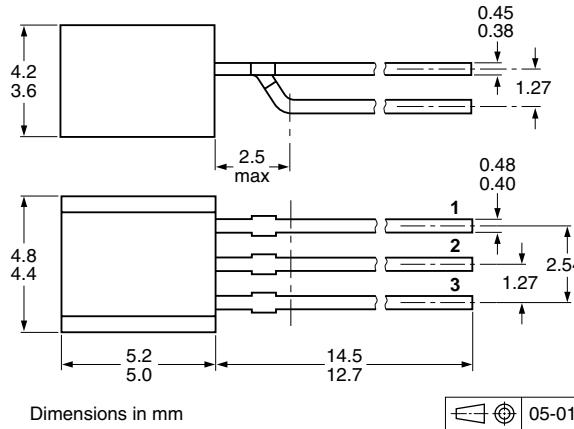
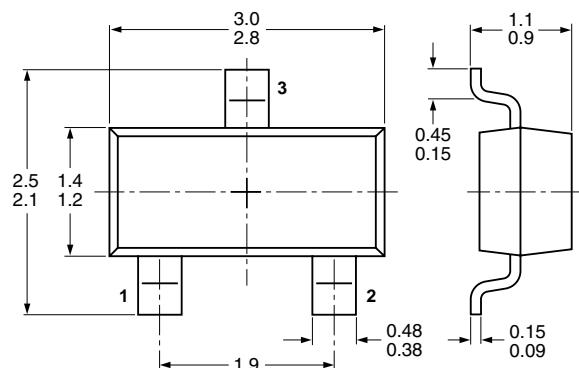
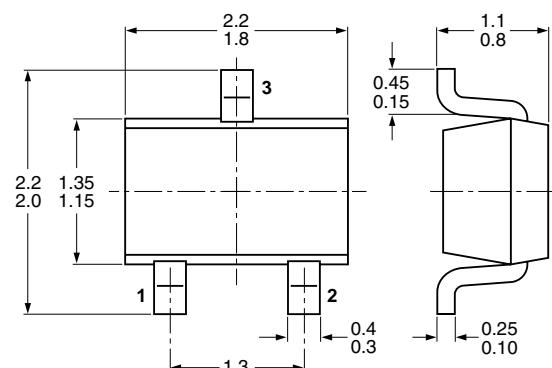


Fig 10. Package outline SOT54 variant



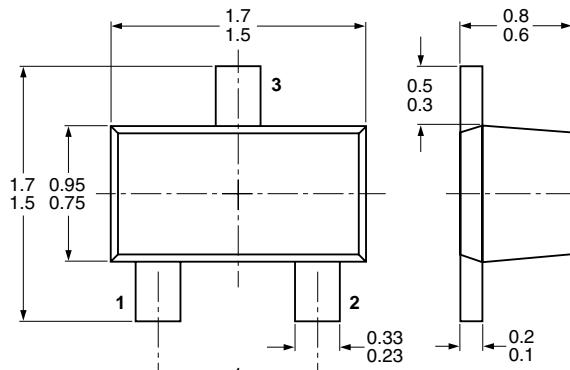
04-11-04



04-11-04

Fig 11. Package outline SOT23 (TO-236AB)

Fig 12. Package outline SOT323 (SC-70)



98-10-23

Fig 13. Package outline SOT490 (SC-89)

9. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity			
			3000	4000	5000	10000
PDTC124XE	SOT416	4 mm pitch, 8 mm tape and reel	-115	-	-	-135
PDTC124XEF	SOT490	4 mm pitch, 8 mm tape and reel	-	-115	-	-
PDTC124XK	SOT346	4 mm pitch, 8 mm tape and reel	-115	-	-	-135
PDTC124XM	SOT883	2 mm pitch, 8 mm tape and reel	-	-	-	-315
PDTC124XS	SOT54	bulk, straight leads	-	-	-412	-
	SOT54A	tape and reel, wide pitch	-	-	-	-116
		tape ammopack, wide pitch	-	-	-	-126
	SOT54 variant	bulk, delta pinning	-	-	-112	-
PDTC124XT	SOT23	4 mm pitch, 8 mm tape and reel	-215	-	-	-235
PDTC124XU	SOT323	4 mm pitch, 8 mm tape and reel	-115	-	-	-135

[1] For further information and the availability of packing methods, see [Section 12](#).

10. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PDTC124X_SER_7	20091116	Product data sheet	-	PDTC124X_SER_6
Modifications:	<ul style="list-style-type: none">This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.			
PDTC124X_SER_6	20050714	Product data sheet	-	PDTC124X_SERIES_5
PDTC124X_SERIES_5	20040813	Product specification	-	PDTC124X_SERIES_4
PDTC124X_SERIES_4	20030410	Product specification	-	PDTC124XEF_2 PDTC124XE_3
PDTC124XE_3	19990518	Product specification	-	PDTC124XE_2
PDTC124XE_2	19980921	Product specification	-	PDTC124XE_1
PDTC124XE_1	19971215	Product specification	-	-
PDTC124XEF_2	19990518	Preliminary specification	-	PDTC124XEF_1
PDTC124XEF_1	19981111	Preliminary specification	-	-

11. Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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